

United States Patent and Trademark Office

COMMISSIONER FOR PATENTS UNITED STATES PATENT AND TRADEMARK OFFICE WASHINGTON, D.C. 20231

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APPLICATION NUMBER

FILING/RECEIPT DATE

FIRST NAMED APPLICANT

ATTORNEY DOCKET NUMBER

10/001,302

P O BOX 655474, M/S 3999

DALLAS, TX 75265

TEXAS INSTRUMENTS INCORPORATED

Edgar R. Zuniga-Ortiz

TI-33535

11/01/2001

CONFIRMATION NO. 2463

Date Mailed: 01/30/2002

FORMALITIES LETTER

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NOTICE TO FILE MISSING PARTS OF NONPROVISIONAL APPLICATION

FILED UNDER 37 CFR 1.53(b)

Filing Date Granted

An application number and filing date have been accorded to this application. The item(s) indicated below, however, are missing. Applicant is given TWO MONTHS from the date of this Notice within which to file all required items and pay any fees required below to avoid abandonment. Extensions of time may be obtained by filing a petition accompanied by the extension fee under the provisions of 37 CFR 1.136(a).

- The oath or declaration is unsigned.
- To avoid abandonment, a late filing fee or oath or declaration surcharge as set forth in 37 CFR 1.16(I) of \$130 for a non-small entity, must be submitted with the missing items identified in this letter.
- The balance due by applicant is \$ 130.

The application is informal since it does not comply with the regulations for the reason(s) indicated below.

The required item(s) identified below must be timely submitted to avoid abandonment:

- Substitute drawings in compliance with 37 CFR 1.84 because:
 - drawing sheets do not have the appropriate margin(s) (see 37 CFR 1.84(g)). Each sheet must include a top margin of at least 2.5 cm. (1 inch), a left side margin of at least 2.5 cm. (1 inch), a right side margin of at least 1.5 cm. (5/8 inch), and a bottom margin of at least 1.0 cm. (3/8 inch);

03/08/2002 NMDHAMM1 00000114 200524 10001308

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A copy of this notice MUST be returned with the reply.

Customer Service Center

Initial Patent Examination Division (703) 308-1202

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pplicant(s): Edgar R. Zuniga-Ortiz, et al.

Art Unit: 2815

Serial No.:

10/001,302

Examiner: TBD

Filed:

11/01/01

Docket: TI-33535

For:

Bumpless Wafer Scale Device and Board Assembly

COPY OF PAPERS ORIGINALLY FILED

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on

as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231.

Kann Vient Karen Vertz <u>) - 25 し</u>2 Date

Assistant Commissioner for Patents Washington, D. C. 20231

Dear Sir:

Enclosed are **THREE** (3) sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated P.O. Box 655474 M/S 3999 Dallas, Texas 75265 (214) 939-8651

Respectfully submitted,

Gary/C. Honeycut

Reg. No. 20,250

Attorney for Applicants



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Docket No.: TI-33535

Art Unit:

Edgar R. Zuniga-Ortiz, et al.

2815

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Assistant Commissioner for

Patents

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Washington, DC 20231

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envelope addressed washington, D.C.	to: Assis	tant	Comm	issioner	for	Pate	nts

Karen Vertz

Date

RESPONSE TO NOTICE TO FILE MISSING PARTS OF APPLICATION

Dear Sir:

In response to the Notice of Missing Parts dated January 30, 2002 please charge the fee of \$130.00 for the surcharge under 37 CFR 1.27 to Deposit Account No. 20-0668 of Texas Instruments Incorporated.

Please find enclosed the Declaration/Power of Attorney (1 page), an Assignment with Form PTO 1595 and formal drawings for the above-referenced case. The Commissioner is hereby authorized to charge any additional fees which may be required. This sheet is submitted in triplicate.

Respectfully submitted,

Gary/C. Honeycutt / Attorney for Applicants

Reg. No. 20,250

Texas Instruments Incorporated Mail Station 3999 P.O. Box 655474 Dallas, TX 75265 (214) 939-8651





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

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ORIGINALLY FILED

Assistant Commissioner for

Patents

Washington, DC 20231

MAILING CERTIF	ICA	TE UND	ER 37 C	.F.R. §1	.8(A)		
I hereby certify that	the	above cor	respond	ence is b	eing d	lepos	ited
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2-15-02		as	First	Class	Mail	in	an
envelope addressed Washington, D.C.							

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Karen Vertz	7	•

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Karen Vertz

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I hereby certify that the above correspondence is being deposited with the U.S. Postal Service on 2-22-22 as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C 20231.

Assistant Commissioner for **Patents** Washington, D. C. 20231

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